UMW FDN337N

N-Channel 30 V (D-S) MOSFET

1.Description

These devices are particularly suited for low voltage applications in notebook computers, portable phones, PCMCIA cards, and other battery powered circuits where fast switching and low in-line power loss are needed in a very small outline surface mount package

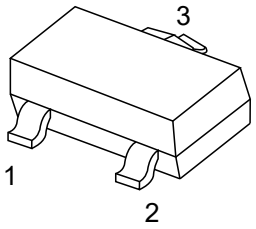
2.Features

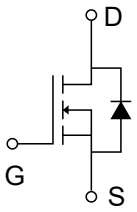
- $V_{DS(V)}$=30V
- I_D=2.2A
- $R_{DS(ON)}$<65mΩ(V_{GS}=4.5V)
- $R_{DS(ON)}$<82mΩ(V_{GS}=2.5V)

3.Pinning information

Pin	Symbol	Description
1	G	GATE
2	S	SOURCE
3	D	DRAIN

SOT-23





4.Maximum ratings (T_A=25°C unless otherwise noted)

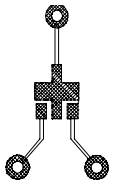
Parameter	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage - Continuous	V_{GSS}	±8	V
Drain/Outpu Current – Continuous	I_D	2.2	A
– Pulsed		10	
Maximum Power Dissipation (Note 1a)	P_D	0.5	W
(Note 1b)		0.46	
Operating and Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	°C
Thermal Characteristics			
Thermal Resistance, Junction-to-Ambient (Note 1a)	$R_{\theta JA}$	250	°C/W
Thermal Resistance, Junction-to-Case (Note 1)	$R_{\theta JC}$	75	°C/W

5.T_A=25°C unless otherwise specified

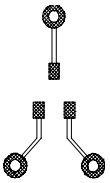
Parameter	Symbol	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
Drain-source breakdown voltage	BV_{DSS}	V_{GS}=0V, I_D=250μA	30			V
Breakdown Voltage Temp. Coefficient	$\Delta BV_{DSS}/\Delta T_J$	I_D=250μA Referenced to 25°C		41		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=24V, V_{GS}=0V			1	μA
		T_J=55°C			10	μA
Gate - Body Leakage, Forward	I_{GSSF}	V_{GS}=8V, V_{DS}=0V			100	nA
Gate - Body Leakage, Reverse	I_{GSSR}	V_{GS}=-8V, V_{DS}=0V			-100	nA
ON CHARACTERISTICS (Note)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	0.4	0.7	1	V
Gate Threshold Voltage Temp. Coefficient	$\Delta V_{GS(th)}/T_J$	I_D=250μA Referenced to 25°C		-2.3		mV/°C
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}=4.5V, I_D=2.2A		54	65	mΩ
		V_{GS}=2.5V, I_D=2A		70	82	
On-State Drain Current	$I_{D(ON)}$	V_{GS}=4.5V, V_{DS}=5V	10			A
Forward Transconductance	g_{FS}	V_{DS}=5V, I_D=2.2A		13		S
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	V_{GS}=0V, V_{DS}=10V, f=1MHz		300		pF
Output Capacitance	C_{oss}			145		pF
Reverse Transfer Capacitance	C_{rss}			35		pF
SWITCHING CHARACTERISTICS (Note)						
Turn - On Delay Time	$t_{D(on)}$	V_{DD}=5V, I_D=1A V_{GS}=4.5V, R_{GEN}=6Ω		4	10	ns
Turn - On Rise Time	t_r			10	18	ns
Turn - Off Delay Time	$t_{D(off)}$			17	28	ns
Turn - Off Fall Time	t_f			4	10	ns

Total Gate Charge	Q_g	V_{DS}=-10V, I_D=-2A V_{GS}=-4.5V		7	9	nC
Gate-Source Charge	Q_{gs}			1.1		nC
Gate-Drain Charge	Q_{gd}			1.9		nC
Drain–Source Diode Characteristics and Maximum Ratings						
Maximum Continuous Drain–Source Diode Forward Current	I_S				0.42	A
Drain–Source Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=0.42A (Note)		0.65	1.2	V

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface ofthe drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.Typical $R_{\theta JA}$ using the board layouts shown below on FR-4 PCB in a still air environment :



a. 250°C/W when mounted on a 0.02 in^2 pad of 2oz Cu.

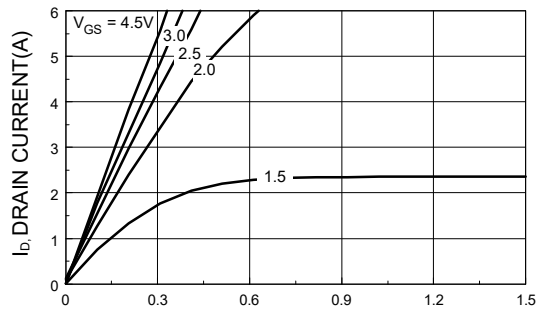


b) 270°C/W when mounted on a 0.001 in^2 pad of 2oz Cu.

Scale 1 : 1 on letter size paper

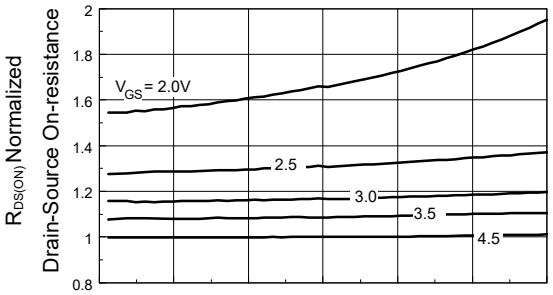
2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

6.1 Typical Characterisitics



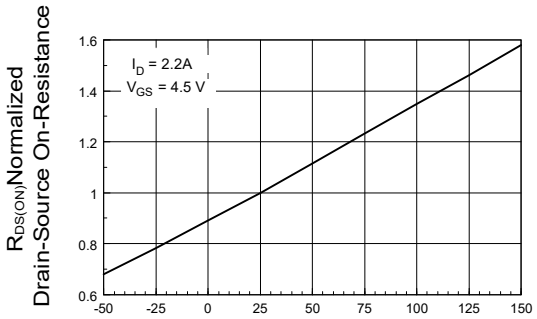
V_{DS} , Drain-Source Voltage (V)

Figure 1: On-Region Characteristics.



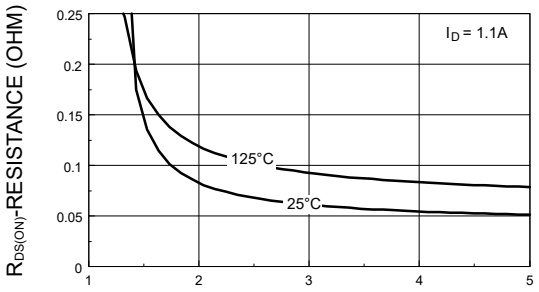
I_D, Drain Current (A)

Figure 2: On-Resistance Variation with Drain Current and Gate Voltage.



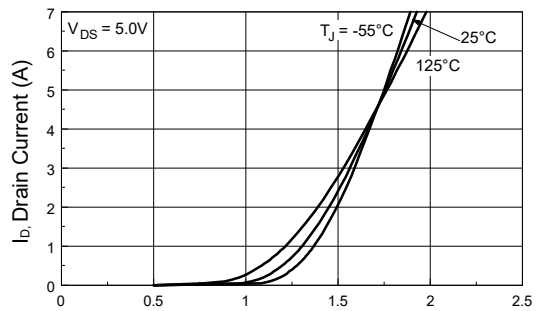
T_J, Junction Temperature (°C)

Figure 3: On-Resistance Variation with Temperature.



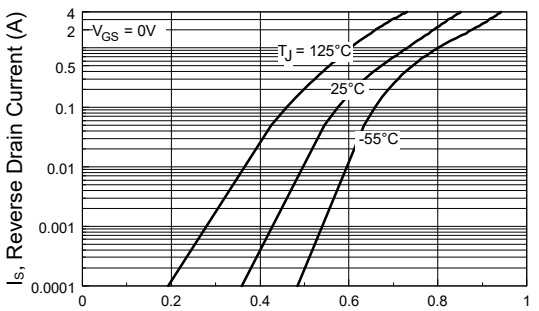
V_{GS}, Gate To Source Voltage (V)

Figure 4: On-Resistance Variation with Gate-to-Source Voltage.



V_{GS}, Gate To Source Voltage (V)

Figure 5: Transfer Characteristics.



V_{SD}, Body Diode Forward Voltage (V)

Figure 6: . Body Diode Forward Voltage Variation with Source Current and Temperature.

6.2 Typical Characterisitics

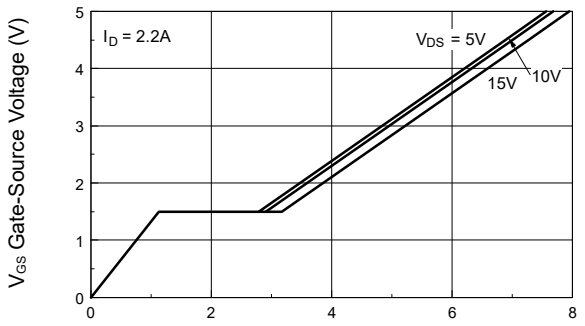


Figure 7: Gate-Charge Characteristics

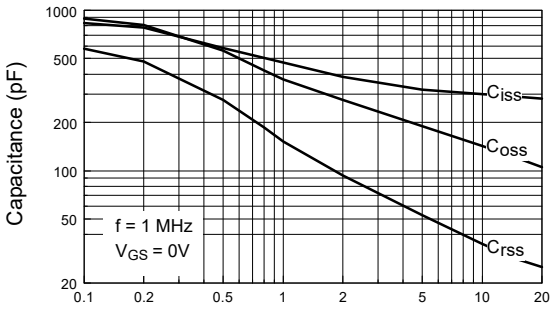


Figure 8: Capacitance Characteristics

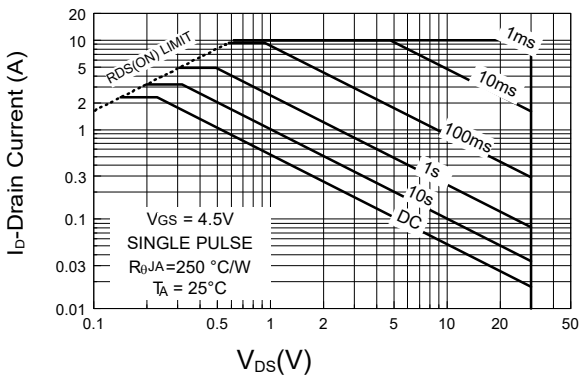


Figure 9: Maximum Safe Operating Area.

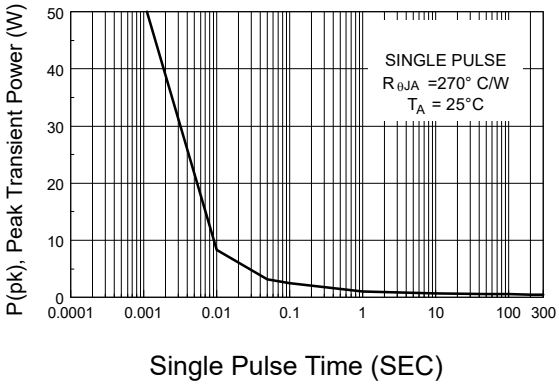


Figure 10: Single Pulse Maximum Power Dissipation.

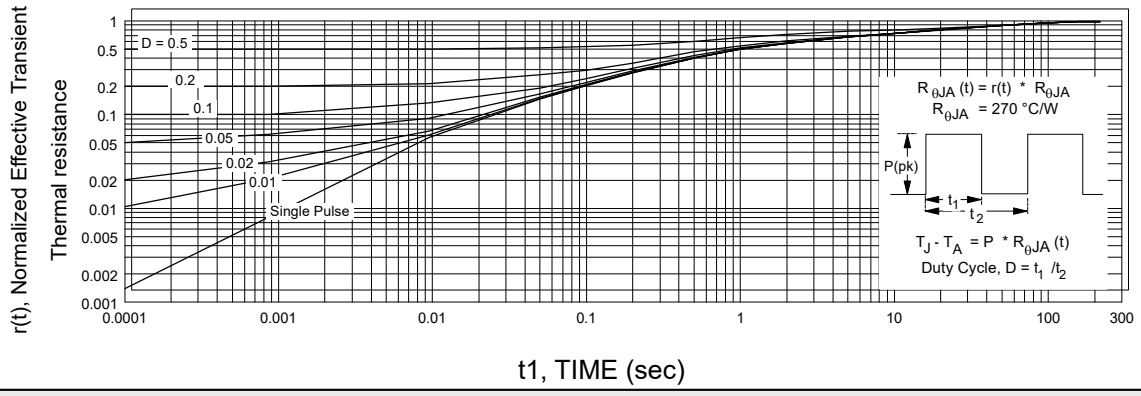
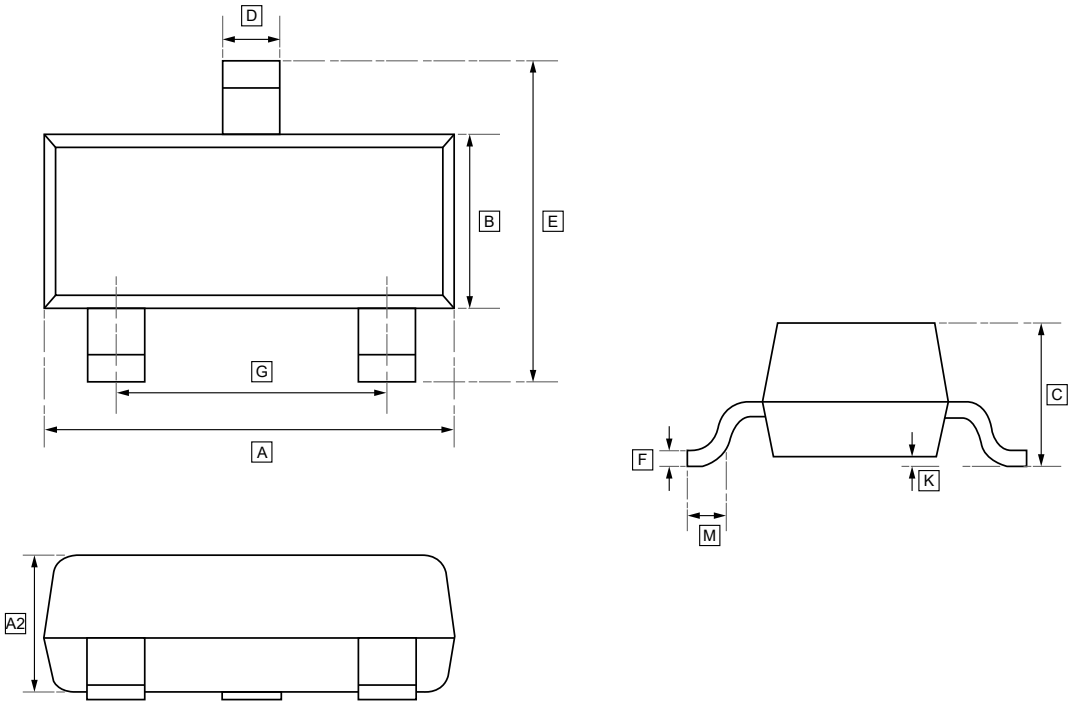


Figure 11. Transient Thermal Response Curve.

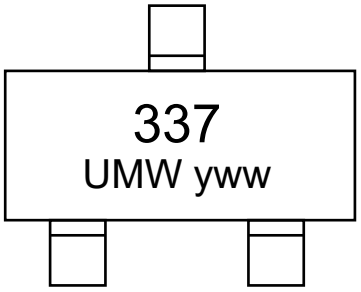
7.SOT-23 Package Outline Dimensions



DIMENSIONS (mm are the original dimensions)

Symbol	A	B	C	D	E	G	K	M	A2	F
Min	2.80	1.20	0.90	0.32	2.25	1.80	0.00	0.30	0.95	0.095
Max	3.04	1.40	1.10	0.55	2.55	2.00	0.10	-	1.05	0.115

8.Ordering Information



yww: Batch Code

Order Code	Package	Base QTY	Delivery Mode
UMW FDN337N	SOT-23	3000	Tape and reel

9.Disclaimer

UMW reserves the right to make changes to all products, specifications. Customers should obtain the latest version of product documentation and verify the completeness and currency of the information before placing an order.

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